ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

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21 Jan 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16095

TITLE: NCP4894DMR2G Expansion Into XFAB-Lubbock

PROPOSED FIRST SHIP DATE: 21 Apr 2008

AFFECTED CHANGE CATEGORY(S): Subcontractor FAB Site

AFFECTED PRODUCT DIVISION(S): Digital Consumer Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Edmond Gallard <edmond.gallard@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is a final process change notice to IPCN #16055. The NCP4894DMR2G device has historically been fabricated at the XFAB facility in Erfurt, Germany, and is now qualified for fabrication at the XFAB facility in Lubbock, TX, USA. All XFAB facilities are certified ISO9001:2000 compliant. XFAB offers the same process technology in both fab locations; no die design or process changes were implemented for this activity. This change is considered a capacity expansion. At the expiration of the FPCN, the NCP4894DMR2G may be processed at either qualified location.

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RELIABILITY DATA SUMMARY:

Qualified by similarity to the NCP4894FCT1G Micro-Bump device already qualified at XFAB Lubbock.

Reliability Test Results:

Test	Conditions	Results
ESD	HBM (2000V), 5 Samples	Pass
	MM (200V), 5 samples	Pass
Latch-Up	>100mA, 6 samples	Pass

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical test characterization was performed on one lot (sample size = 35 units) processed at XFAB Lubbock. The results were compared to data for the same device fabricated at the XFAB Erfurt wafer fab. No change in performance was observed.

CHANGED PART IDENTIFICATION:

There will be no changes to the topside part marking. Part traceability will be maintained in accordance with the ON Semiconductor policy.

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AFFECTED DEVICE LIST

NCP4894DMR2G